

DMP1012USS-13 Datasheet



DiGi Electronics Part Number	DMP1012USS-13-DG
Manufacturer	Diodes Incorporated
Manufacturer Product Number	DMP1012USS-13
Description	MOSFET BVDSS: 8V-24V SO-8 T&R 2.
Detailed Description	P-Channel 12 V 8.5A (Ta) 1.3W (Ta)

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Purchase and inquiry

Manufacturer Product Number:

DMP1012USS-13

Series:

-

FET Type:

P-Channel

Drain to Source Voltage (Vdss):

12 V

Drive Voltage (Max Rds On, Min Rds On):

1.8V, 4.5V

Vgs(th) (Max) @ Id:

1V @ 250µA

Vgs (Max):

±8V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

-

Base Product Number:

DMP1012

Manufacturer:

Diodes Incorporated

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

8.5A (Ta)

Rds On (Max) @ Id, Vgs:

15mOhm @ 9A, 4.5V

Gate Charge (Qg) (Max) @ Vgs:

19.5 nC @ 4.5 V

Input Capacitance (Ciss) (Max) @ Vds:

1344 pF @ 10 V

Power Dissipation (Max):

1.3W (Ta)

Mounting Type:

-

Package / Case:

-

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



DMP1012USS

12V P-CHANNEL ENHANCEMENT MODE MOSFET

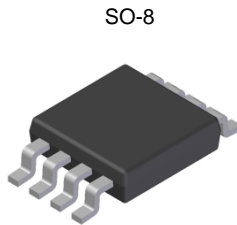
Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
-12V	15mΩ @ V _{GS} = -4.5V	-8.5A
	20mΩ @ V _{GS} = -3.7V	-7.3A
	25mΩ @ V _{GS} = -3.3V	-6.6A
	30mΩ @ V _{GS} = -2.5V	-6.0A
	40mΩ @ V _{GS} = -1.8V	-5.2A

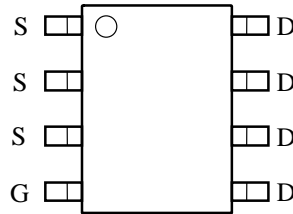
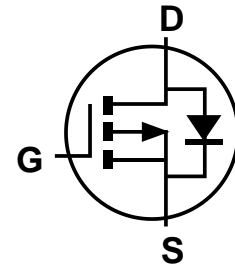
Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- Power Management Functions
- DC-DC Converters



Top View

Top View
Internal Schematic

Equivalent Circuit

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

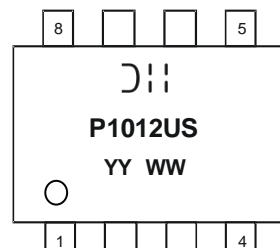
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish — Matte Tin Annealed over Copper Lead Frame. Solderable per MIL-STD-202, Method 208^(e3)
- Weight: 0.074 grams (Approximate)

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1012USS-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



⑆ = Manufacturer's Marking
 P1012US = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Year (ex: 18 = 2018)
 WW = Week (01 to 53)



DMP1012USS

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-12	V	
Gate-Source Voltage	V _{GSS}	±8	V	
Continuous Drain Current (Note 6) V _{GS} = -4.5V	I _D	Steady State T _A = +25°C	-8.5	A
		T _A = +70°C	-6.8	A
Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%)	I _{DM}	-40	A	
Maximum Continuous Body Diode Forward Current (Note 6)	I _S	-2	A	
Pulsed Body Diode Forward Current (10μs Pulse, Duty Cycle = 1%)	I _{SM}	-40	A	
Avalanche Current (Note 7) L = 0.1mH	I _{AS}	-21	A	
Avalanche Energy (Note 7) L = 0.1mH	E _{AS}	22	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	P _D	Steady State T _A = +25°C	1.3	W
Thermal Resistance, Junction to Ambient (Note 5)		R _{θJA}	Steady state	99
Total Power Dissipation (Note 6)	P _D	Steady State T _A = +25°C	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)		R _{θJA}	Steady state	77
Thermal Resistance, Junction to Case (Note 6)	R _{θJC}		13	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}		-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-12	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	μA	V _{DS} = -9.6V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	-0.4	—	-1.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	9	15	mΩ	V _{GS} = -4.5V, I _D = -9A
			10	20		
			11	25		
			13	30		
			18	40		
Diode Forward Voltage	V _{SD}	—	-0.8	-1.2	V	V _{GS} = 0V, I _S = -1A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	1344	—	pF	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	342	—		
Reverse Transfer Capacitance	C _{rss}	—	297	—		
Gate Resistance	R _g	—	15	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = -4.5V)	Q _g	—	19.5	—	nC	V _{DS} = -6V, I _D = -10A
Total Gate Charge (V _{GS} = -8V)	Q _g	—	31	—		
Gate-Source Charge	Q _{gs}	—	2.1	—		
Gate-Drain Charge	Q _{gd}	—	7.9	—		
Turn-On Delay Time	t _{D(ON)}	—	6.0	—	ns	V _{DS} = -6V, V _{GS} = -4.5V, R _g = 1Ω, I _D = -8A
Turn-On Rise Time	t _R	—	32	—		
Turn-Off Delay Time	t _{D(OFF)}	—	71	—		
Turn-Off Fall Time	t _F	—	85	—		
Reverse Recovery Time	t _{RR}	—	46	—	ns	I _F = -12A, di/dt = 500A/μs
Reverse Recovery Charge	Q _{RR}	—	44	—	nC	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 - I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.



DMP1012USS

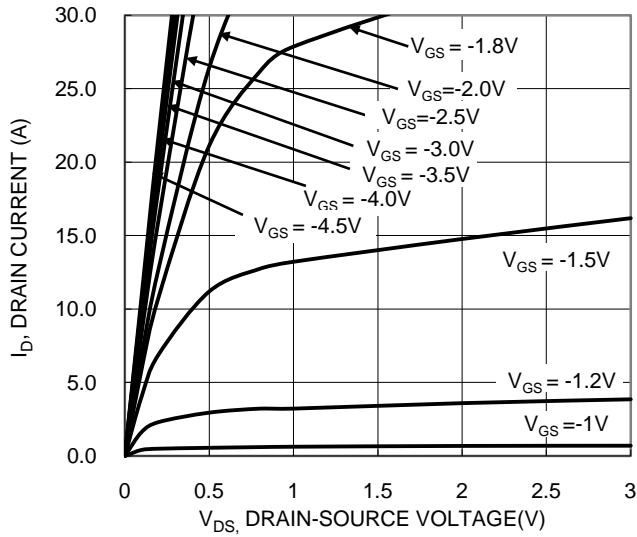


Figure 1. Typical Output Characteristic

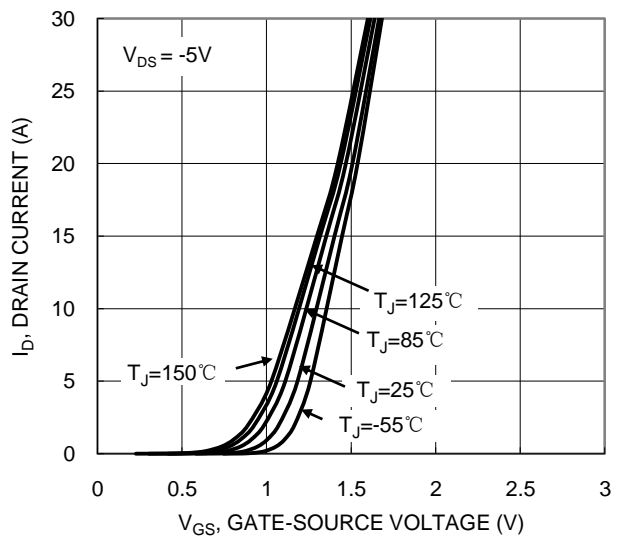


Figure 2. Typical Transfer Characteristic

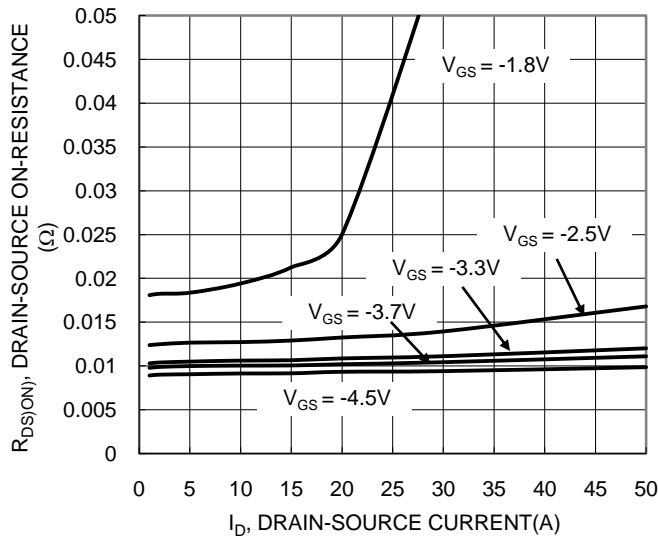


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

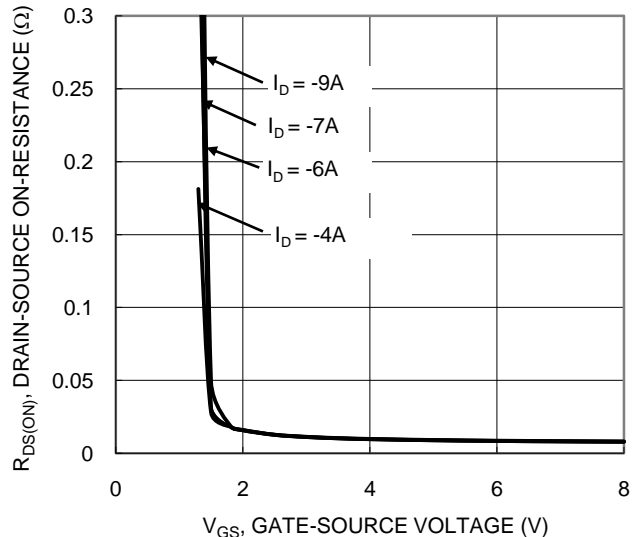


Figure 4. Typical Transfer Characteristic

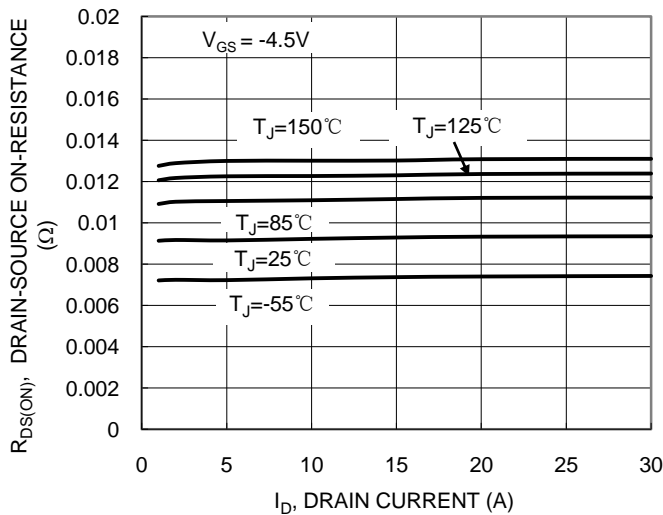


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

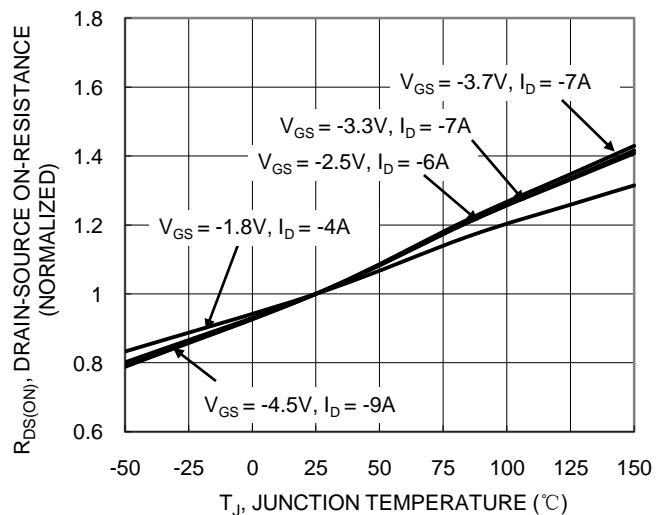


Figure 6. On-Resistance Variation with Junction Temperature



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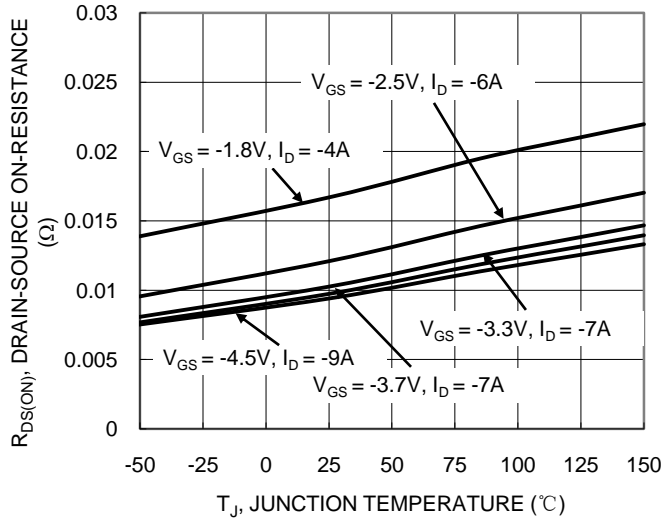


Figure 7. On-Resistance Variation with Junction Temperature

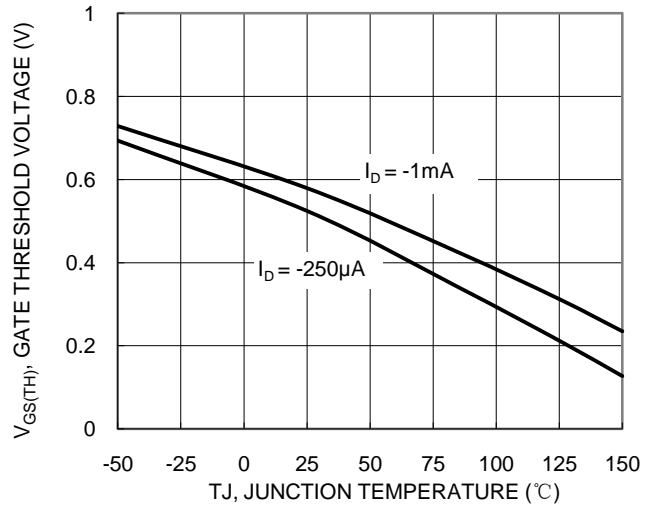


Figure 8. Gate Threshold Variation vs. Junction Temperature

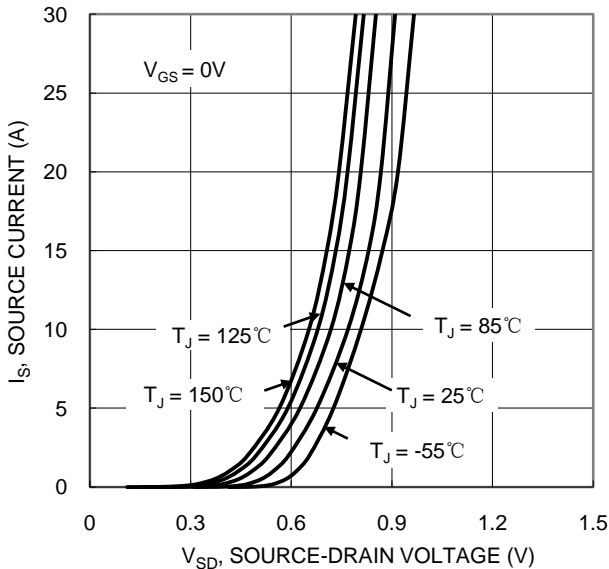


Figure 9. Diode Forward Voltage vs. Current

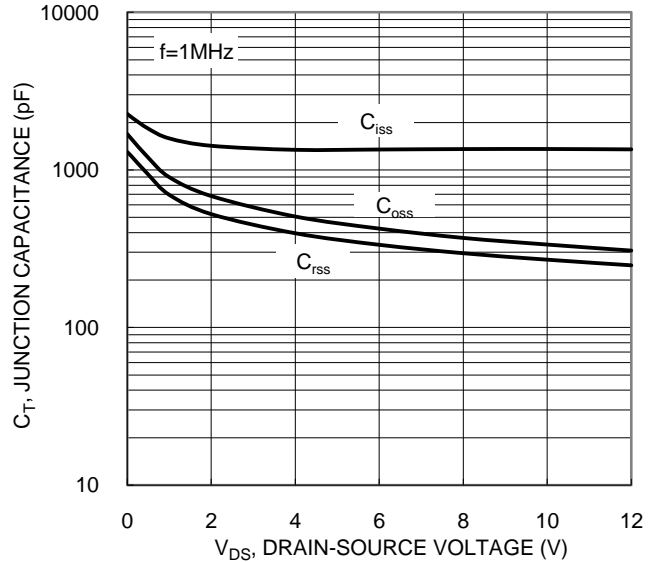


Figure 10. Typical Junction Capacitance

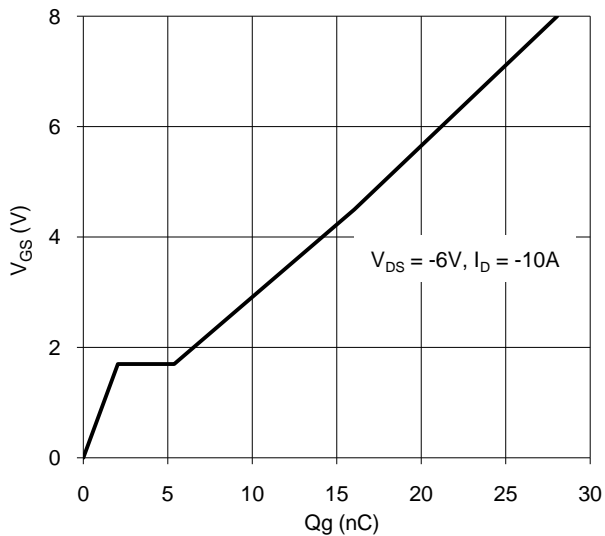


Figure 11. Gate Charge

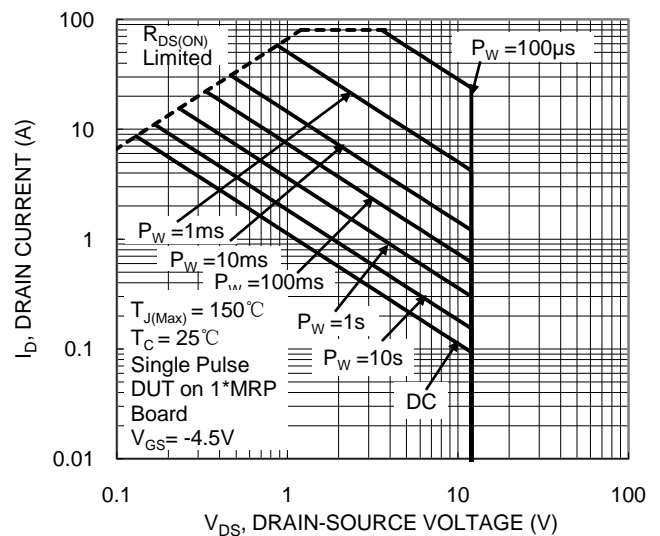


Figure 12. SOA, Safe Operation Area



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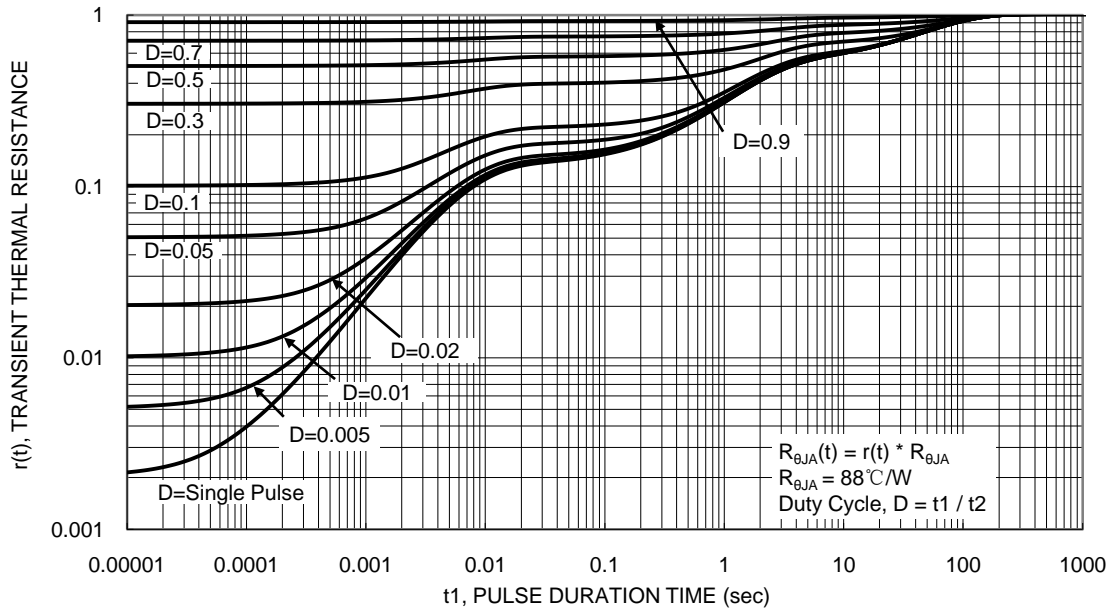


Figure 13. Transient Thermal Resistance

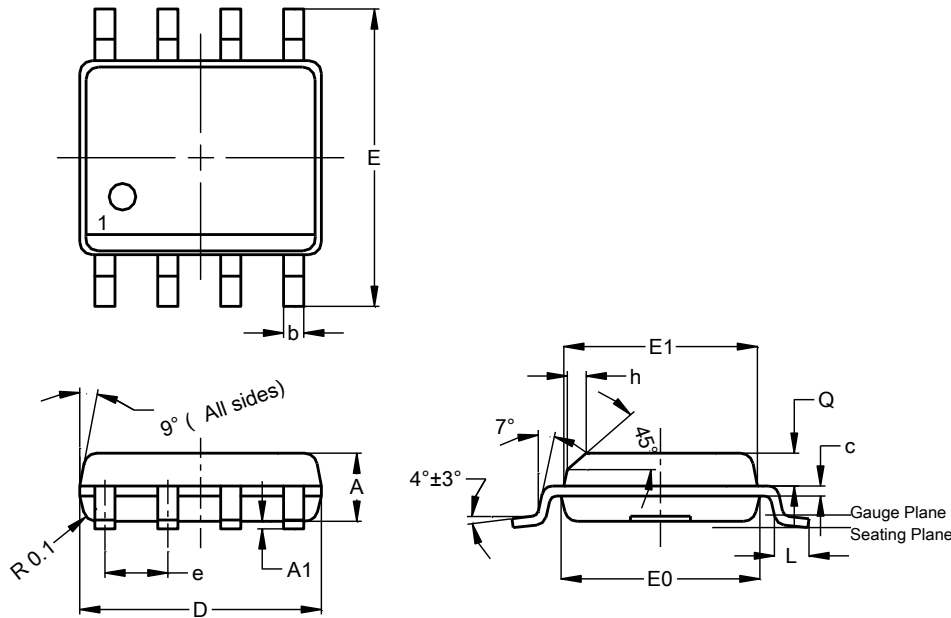


DMP1012USS

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

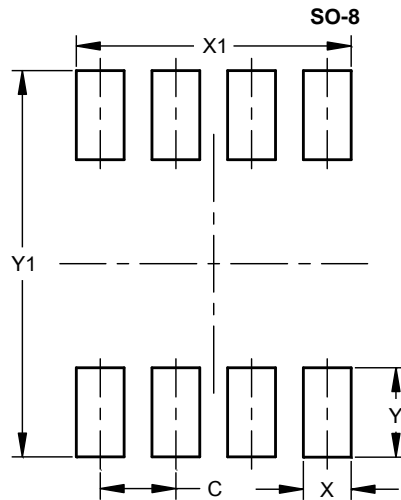
SO-8



SO-8			
Dim	Min	Max	Typ
A	1.40	1.50	1.45
A1	0.10	0.20	0.15
b	0.30	0.50	0.40
c	0.15	0.25	0.20
D	4.85	4.95	4.90
E	5.90	6.10	6.00
E1	3.80	3.90	3.85
E0	3.85	3.95	3.90
e	--	--	1.27
h	-	--	0.35
L	0.62	0.82	0.72
Q	0.60	0.70	0.65
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



Dimensions	Value (in mm)
C	1.27
X	0.802
X1	4.612
Y	1.505
Y1	6.50



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